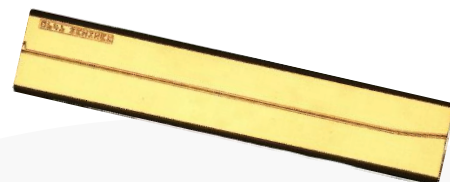


High Power SOA Chip



Part Number: CHP-288

High Power SOA Chip
Single-Mode SOA Fabry-Perot
Wavelength at 1310nm



Features

- High Output Power
- High Dynamic Range
- High Efficiency
- Standard SOA Bare Die
- Cost Effective

Application

- OTDR
- LiDAR
- Free Space Communications
- Network Test Equipment



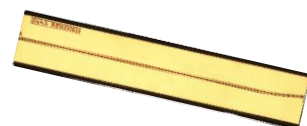
SemiNex delivers the highest available power at infrared wavelengths between 12xx and 19xx nm. When necessary, we will further optimize the design of our InP & GaSb laser chips to meet our customers' specific optical and electrical performance needs. Diodes, bars and packages are tested to meet customer and market performance demands. Typical results and packaging options are shown. Contact SemiNex for additional details or to discuss your specific requirements.

High Power SOA Chip



Specification

CHP-288



Optical	Symbol	Typ.	Units
Center Wavelength	λ_c	1310	nm
Output Power @1A*	P _{out}	0.45	watts (±10%)
Aperture Width	AW	4	μm
Aperture Height	AH	1	μm
Gain @ Pin = 10μW	G	35	dB
Beam Exit Angle	θ_{EXT}	19.5	Degree
Noise Figure	NF	6	dB
Polarization Extinction Ratio	PER	18	dB
Fast Axis Div.	θ_{\perp}	28	Deg FWHM
Slow Axis Div.	θ_{\parallel}	16	Deg FWHM
Front Facet Reflectivity		<0.1%	
Rear Face Reflectivity		<0.1%	
Waveguide		Curved	
Electrical	Symbol		Units
Operating Current	I _{op}	1	A
Operating Voltage	V _{op}	2	V
Mechanical		Range	Units
Chip Length		2500	μm
Chip Width		500	μm
Operating Temp.**		-20 to 75	°C
Storage Temp.		-40 to 85	°C

*Optical Power for 1310nm Chips CHP-288 and CHP-290 has an SOA current @ 1.2A and Pin @ 7mW
 *Optical Power for 1550nm Chips CHP-285 and CHP-287 has an SOA current @ 1.4A and Pin @ 36mW

*Specified values are rated at a constant heat sink temperature of 20°C.
 **High temperature operation will reduce performance and MTTF.
 Unless otherwise indicated all values are nominal.

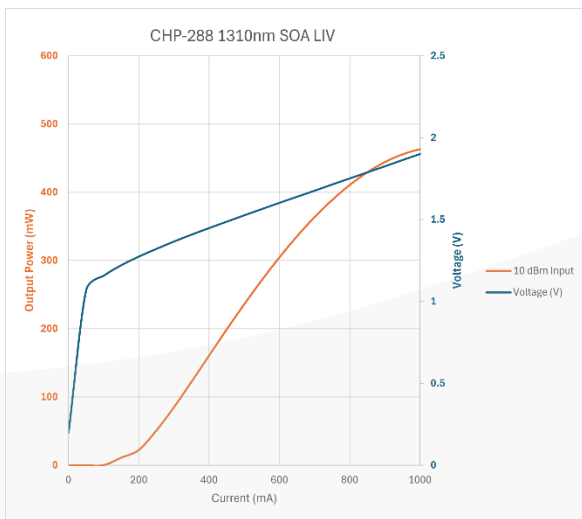
High Power SOA Chip



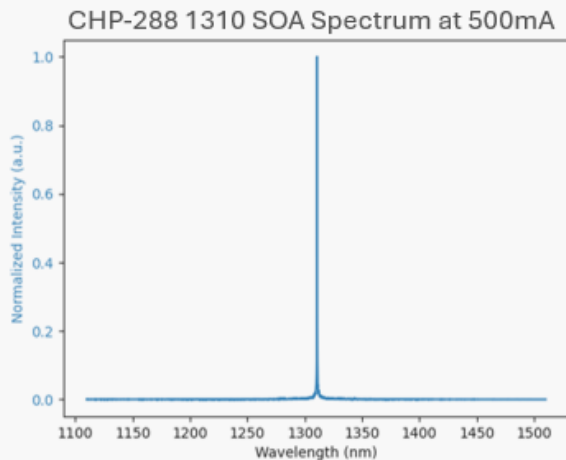
SemiNex Laser Diodes CHP-288

Graphs & Data

Typical CHP L-I-V Characteristics



Typical CHP Output Spectrum



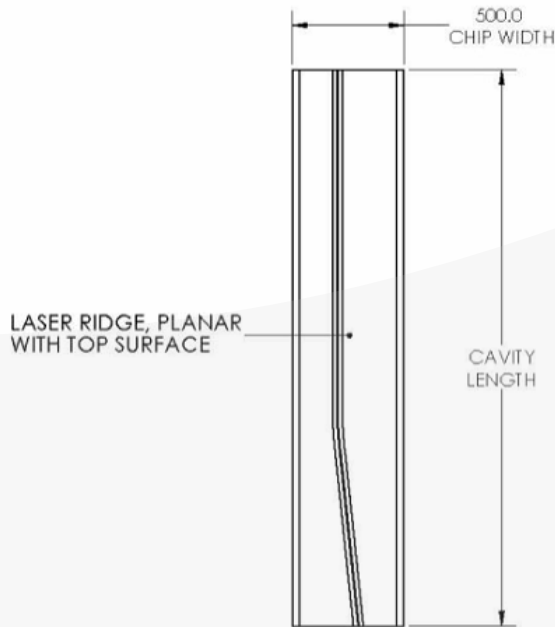
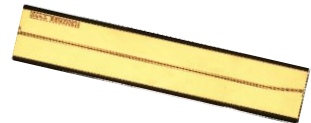
*Graphs and Data were collected from mounted parts

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High Power SOA Chip



Mechanical Drawing



CHIP ATTRIBUTES	
WAVELENGTH	1550nm ±20nm
APERTURE WIDTH	4µm ±1µm
CHIP WIDTH	0.500mm ±10µm
THICKNESS	160µm ±10µm
CAVITY LENGTH	2.5mm ±10µm

P-METAL		
MATERIAL	THICKNESS (nm)	TOLERANCE (nm)
Ti	50	±10
Pt	125	±25
Au	250	±50

N-METAL		
MATERIAL	THICKNESS (nm)	TOLERANCE (nm)
Ti	30	±10
Pt	125	±25
Au	400	±40



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